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(12) **United States Design Patent**
Chen et al.

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(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
USPC D13/110, 182; 257/668, 678, 690; 361/713, 679.01, 728, 736, 760, 761, 361/775, 820; 324/71.5, 252; 174/250, 253; 438/64, 65, 66
See application file for complete search history.

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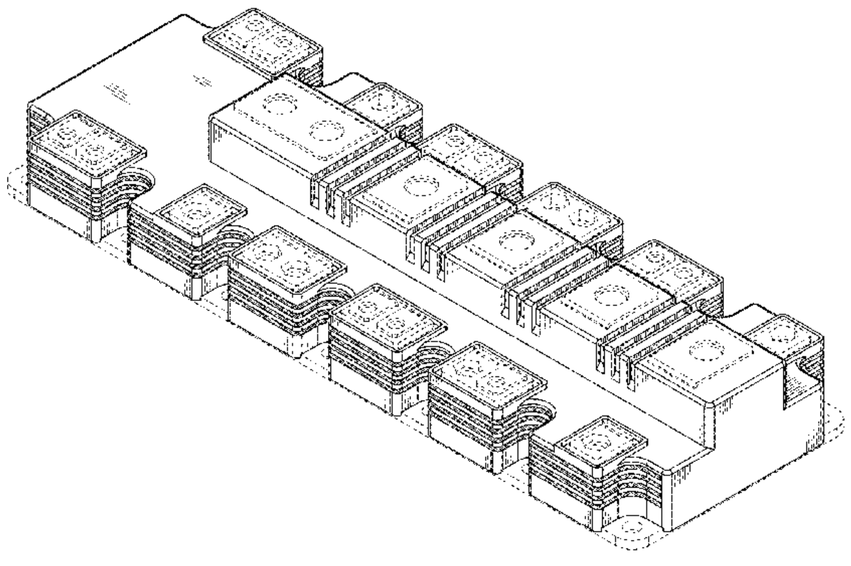
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a semiconductor device showing our new design;
FIG. **2** is a rear view of the semiconductor device of FIG. **1**;
FIG. **3** is a left side view of the semiconductor device of FIG. **1**;
FIG. **4** is a right side view of the semiconductor device of FIG. **1**;
FIG. **5** is a top view of the semiconductor device of FIG. **1**;
FIG. **6** is a bottom view of the semiconductor device of FIG. **1**;
FIG. **7** is a top, front and right side perspective view of the semiconductor device of FIG. **1**; and,
FIG. **8** is a top, rear and left side perspective view of the semiconductor device of FIG. **1**.
The broken lines shown in the drawings represent portions of the semiconductor device that form no part of the claimed design.

1 Claim, 8 Drawing Sheets



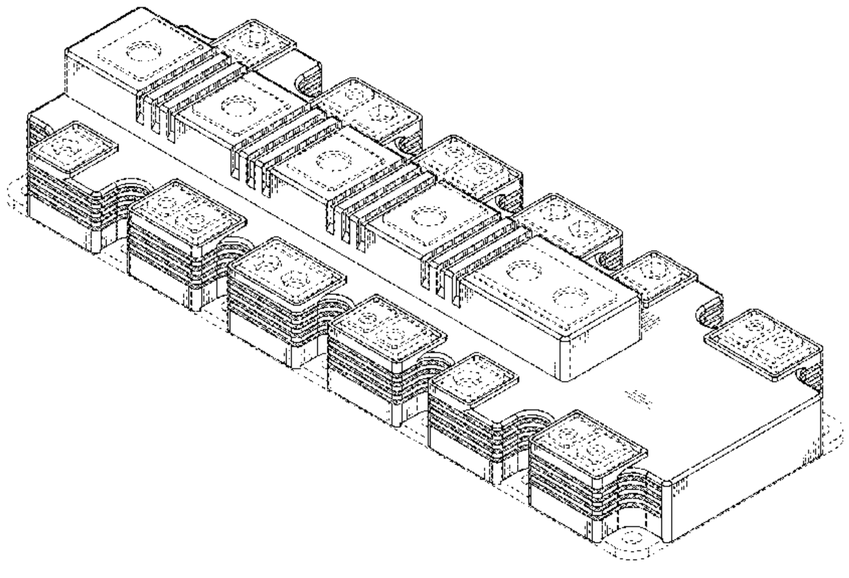


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Fig.1

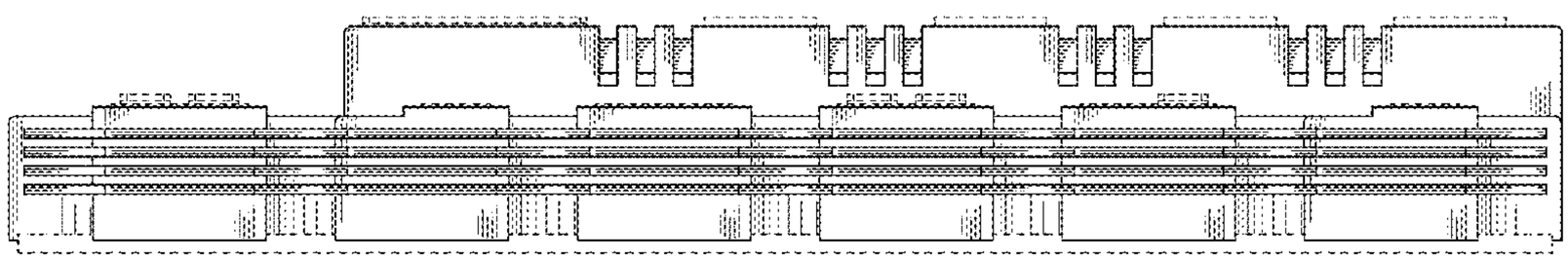

Fig.2

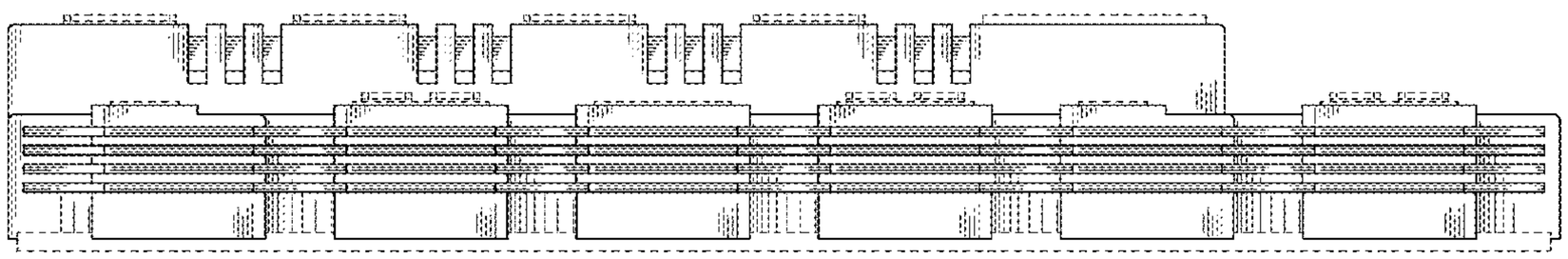

Fig.3

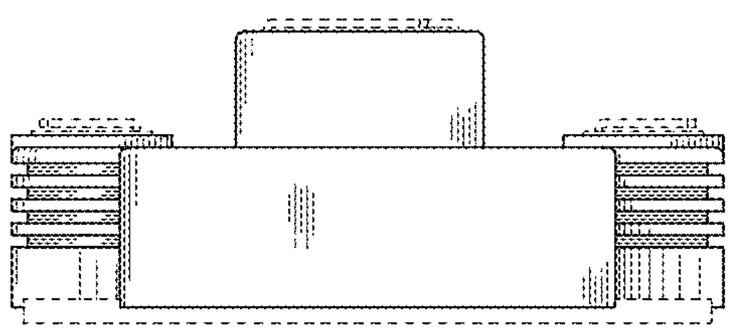

Fig.4

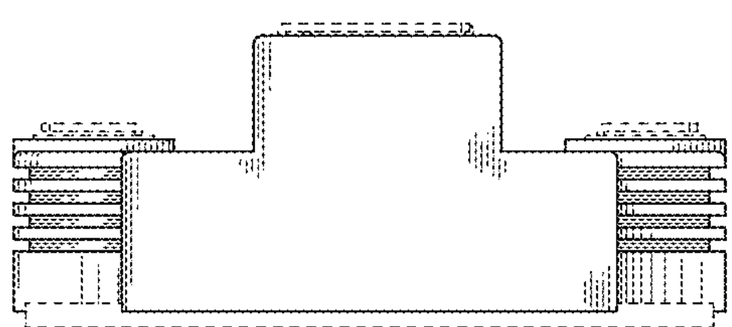

Fig.5

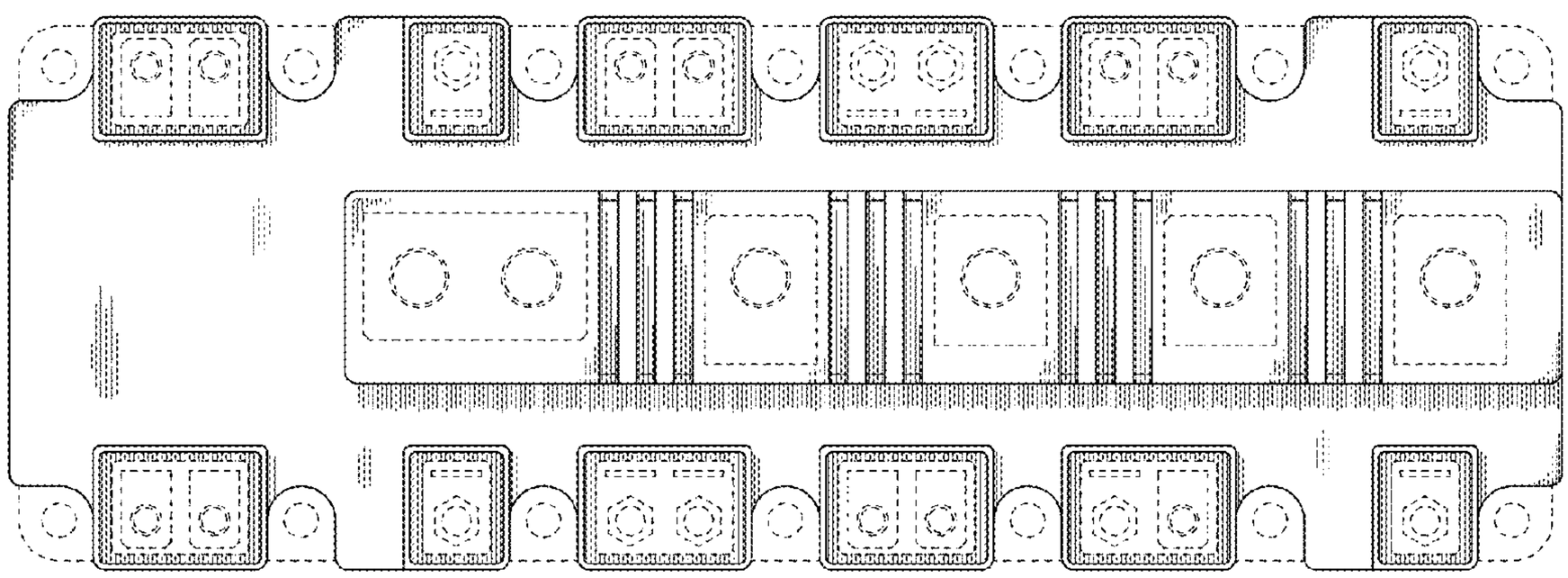

Fig.6

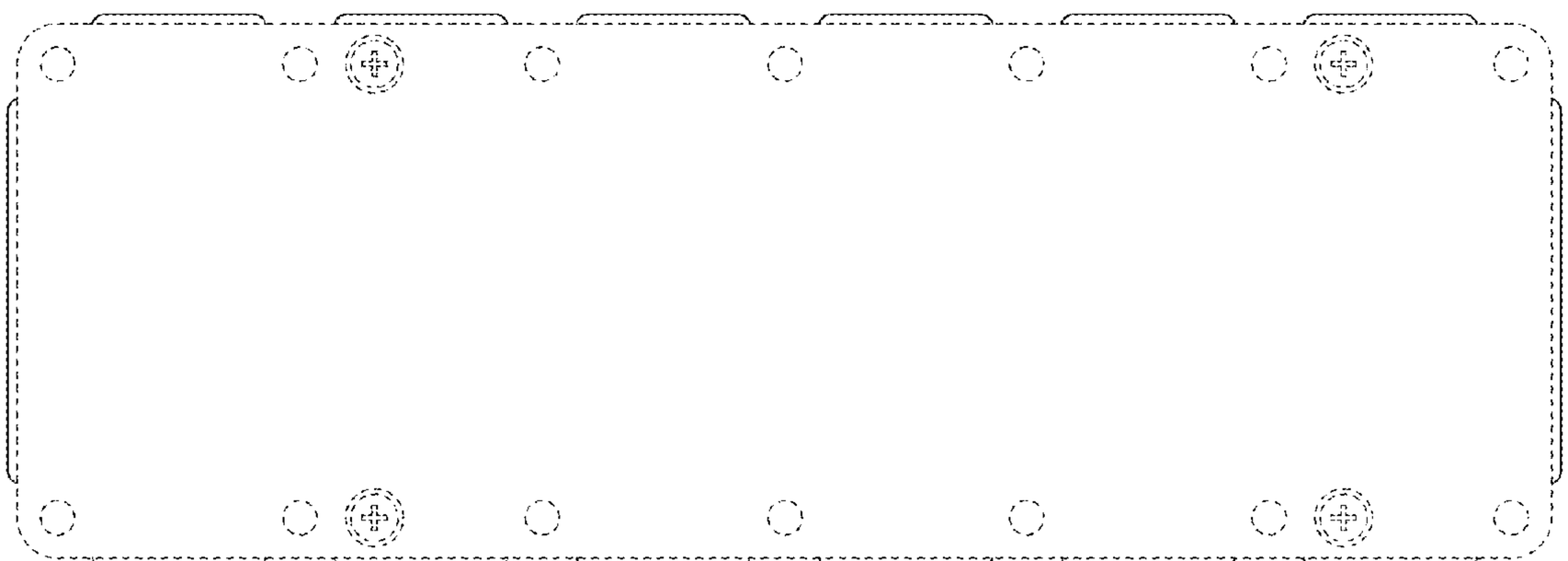

Fig.7

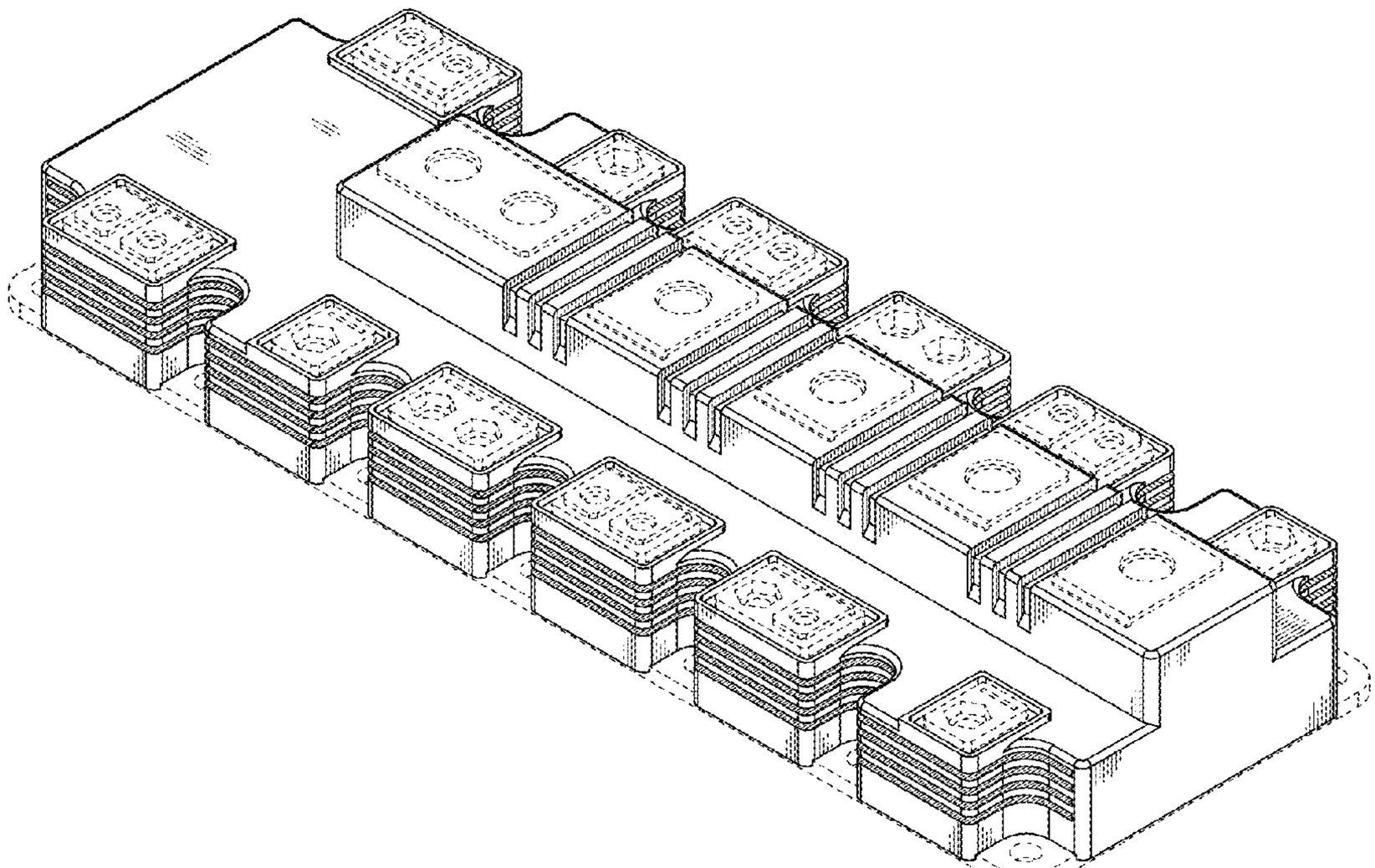

Fig.8